



Technical Data Sheet

Solder Paste SnAg3,5-P-WL449-8 Series

Description	Soft solder paste for surface mount printing applications.																																																	
Key Benefits	<ul style="list-style-type: none"> - Excellent printing properties - Low void rates - Good cleaning properties 			Compliant Products																																														
Product Code and Alloy	<table border="1"> <thead> <tr> <th colspan="2"></th> <th colspan="2">Code</th> <th colspan="2">Powder Properties</th> <th colspan="3">Application</th> </tr> <tr> <th>Paste</th> <th>Alloy</th> <th>Metal Content</th> <th>Viscosity</th> <th>Powder Type</th> <th>Particle Size</th> <th>Alloy</th> <th>Melting Point</th> <th>Stencil Printing</th> <th>Screen Printing</th> <th>Dispensing</th> </tr> </thead> <tbody> <tr> <td>WL449</td> <td>Ag3,5</td> <td>88</td> <td>P</td> <td>2</td> <td>45 - 75 µm</td> <td>Sn/Ag3,5</td> <td>221°C</td> <td><input checked="" type="checkbox"/></td> <td><input checked="" type="checkbox"/></td> <td><input type="checkbox"/></td> </tr> <tr> <td>WL449</td> <td>Ag3,5</td> <td>88</td> <td>P</td> <td>3</td> <td>25 - 45 µm</td> <td>Sn/Ag3,5</td> <td>221°C</td> <td><input checked="" type="checkbox"/></td> <td><input checked="" type="checkbox"/></td> <td><input type="checkbox"/></td> </tr> </tbody> </table>				Code		Powder Properties		Application			Paste	Alloy	Metal Content	Viscosity	Powder Type	Particle Size	Alloy	Melting Point	Stencil Printing	Screen Printing	Dispensing	WL449	Ag3,5	88	P	2	45 - 75 µm	Sn/Ag3,5	221°C	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	WL449	Ag3,5	88	P	3	25 - 45 µm	Sn/Ag3,5	221°C	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
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Flux Activity	No Clean <input type="checkbox"/>	Water Washable <input checked="" type="checkbox"/>	ISO 9454-1:1990 [DIN EN 29454-1:1993] not tested	J-STD-004A:2004 ORLO	Bellcore GR-78-Core [Issue 1:1997] not tested	Siemens Norm [SN 59650:1998] not tested																																												
Halogen Content	Halogen Free <input type="checkbox"/> <small>Halogen Free - Tolerances from IEC 61249-2-21: Cl or Br <900 ppm, total <1500 ppm; measured according BS EN 14582</small>			Halogen Zero - No Halogen added in the Flux: <input checked="" type="checkbox"/> <small>Halogen Zero - Tolerance: Halogen < 50 ppm; measured according BS EN 14582</small>																																														
Paste Conditioning	Remove paste from fridge: Before opening the package leave paste 2 hours at room temperature so that paste warms up. Do not open cartridge while paste is cold to prevent condensation of moisture on the paste - this causes defects, e.g. solder balling etc. Do not heat the paste.																																																	
Reflow	Peak temperature: 20-30°C above the melting temperature of the alloy. Time above melting temperature: 30 to 90 seconds.																																																	
Cleaning	For cleaning of wet paste, or if desired for cleaning of flux residues, Zestron and Vigon cleaners can be used. Flux residues have to be removed within max. 4h after reflow by spraying DI water of min. 50°C. For alternative cleaning methods see separate cleaning recommendations.																																																	
Storage	Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity. Max expiration date : please refer to the expiry date on the label of the packaged product. Storage conditions in the refrigerator at 2-10°C.																																																	
Contact	www.heraeus-contactmaterials.com			Version	TDS_Solder Paste SnAg3,5-P-WL449-8 Series_25.Oct. 2013																																													

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